

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS76801QPWPG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS76801QPWPG4	NIPDAU	Level-2-260C-1 YEAR	TI TAIWAN A/T	PWP 20	4.4x6.5x1.15	74.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.090408	99.990046	999900	0.1207	1207
Not Categorized	Proprietary Materials		0.000007	0.007742	77	0.000009	0
Precious Metals	Silver	7440-22-4	0.000002	0.002212	22	0.000003	0
Sub-Total			0.090417	100	1000000	0.120712	1207
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.460004	69.999954	700000	0.614134	6141
Thermoplastics	Epoxy	85954-11-6	0.197145	30.000046	300000	0.263201	2632
Sub-Total			0.657149	100	1000000	0.877336	8773
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	27.85926	97.41	974100	37.193877	371939
Copper and Its Alloys	Iron	7439-89-6	0.6864	2.4	24000	0.916387	9164
Copper and Its Alloys	Phosphorus	7723-14-0	0.00858	0.03	300	0.011455	115
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00858	0.03	300	0.011455	115
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00858	0.03	300	0.011455	115
Zinc and Its Alloys	Zinc	7440-66-6	0.0286	0.1	1000	0.038183	382
Sub-Total			28.6	100	1000000	38.182812	381828
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.437552	95.12	951200	0.58416	5842
Precious Metals	Gold	7440-57-5	0.003588	0.78	7800	0.00479	48
Precious Metals	Palladium	7440-05-3	0.01886	4.1	41000	0.025179	252
Sub-Total			0.46	100	1000000	0.614129	6141
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	36.017916	85	850000	48.086199	480862
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	0.508488	1.199999	12000	0.678864	6789
Other Plastics and Rubber	Carbon Black	1333-86-4	0.127122	0.3	3000	0.169716	1697
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.127122	0.3	3000	0.169716	1697
Other Plastics and Rubber	Silicone	218163-11-2	1.271221	3.000001	30000	1.697161	16972
Thermoplastics	Epoxy	85954-11-6	4.32215	10.2	102000	5.770344	57703
Sub-Total			42.374019	100	1000000	56.572	565720
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.721228	100	1000000	3.633012	36330
Sub-Total			2.721228	100	1000000	3.633012	36330
Total			74.902813			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.